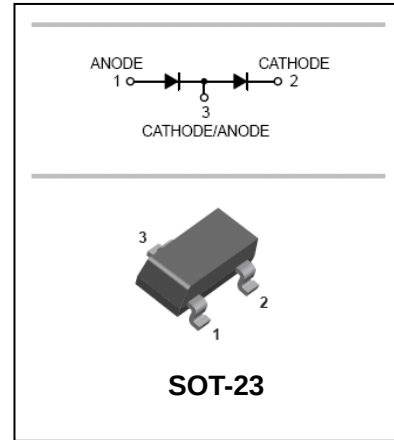


Surface mount switching diode**DAN217****FEATURES**

- Small surface mounting type.(UMD3,SMD3)
- Two diode elements are connected in series.

**APPLICATIONS**

- High speed switching application.

ORDERING INFORMATION

Type No.	Marking	Package Code
DAN217	BA1	SOT-23

MAXIMUM RATING @ Ta=25°C unless otherwise specified

Characteristic	Symbol	Limits	Unit
Peak Reverse Voltage	V_{RM}	80	V
DC Reverse Voltage	V_R	80	V
Maximum (peak)forward Current	I_{FM}	300	mA
Forward Continuous Current	I_o	100	mA
Surge Current (1μs)	I_{FSM}	4000	mA
Power Dissipation	P_d	200	mW
Operating Junction Temperature Range	T_j	125	°C
Storage Temperature Range	T_{STG}	-55 to +125	°C

ELECTRICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified

Characteristic	Symbol	Min	MAX	UNIT	Test Condition
Reverse Breakdown Voltage	$V_{(BR)R}$	80		V	$I_R = 100\mu A$
Forward Voltage	V_F		1.2	V	$I_F = 100mA$
Reverse Leakage Current	I_R		0.1	μA	$V_R = 70V$

Surface mount switching diode

DAN217

TYPICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified

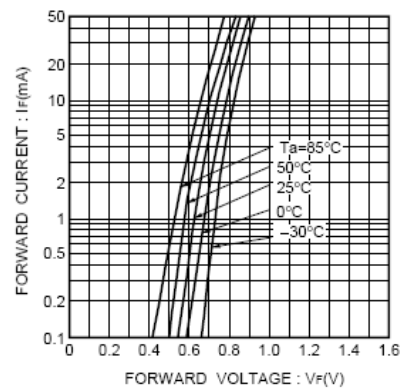


Fig.4 Forward characteristics

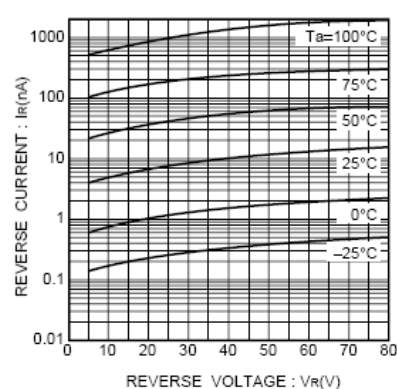


Fig.5 Reverse characteristics

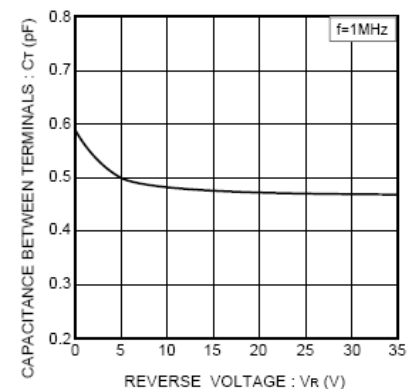


Fig.6 Capacitance between terminals characteristics

PACKAGE OUTLINE

Plastic surface mounted package

SOT-23

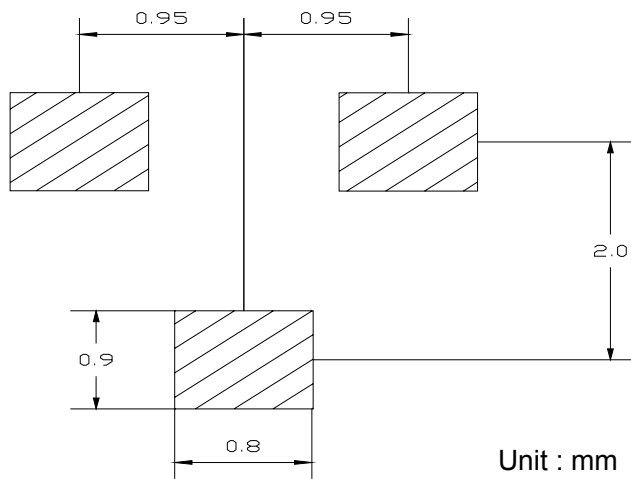
The mechanical drawing shows three views of the SOT-23 package: a top view with dimensions A (width) and B (height), a side view with dimensions C (thickness), D (lead width), E (lead height), and G (pitch), and a bottom view with dimensions H (lead thickness) and J (lead length). The package is a plastic surface-mounted device with two leads.

SOT-23		
Dim	Min	Max
A	2.85	2.95
B	1.25	1.35
C	1.0Typical	
D	0.37	0.43
E	0.35	0.48
G	1.85	1.95
H	0.02	0.1
J	0.1Typical	
K	2.35	2.45
All Dimensions in mm		

Surface mount switching diode

DAN217

SOLDERING FOOTPRINT



PACKAGE INFORMATION

Device	Package	Shipping
DAN217	SOT-23	3000/Tape&Reel